

NSR05T30XV2

500 mA, 30 V Schottky Barrier Diode

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current that offers the most optimal power dissipation in applications. They are housed in spacing saving micro-packaging ideal for space constraint applications.

Features

- Low Forward Voltage Drop – 370 mV (Typ.) @ $I_F = 500$ mA
- Low Reverse Current – 52 μ A (Typ.) @ $V_R = 30$ V
- 500 mA of Continuous Forward Current
- High Switching Speed
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

MAXIMUM RATINGS

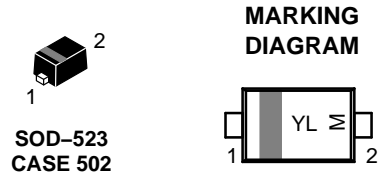
| Rating | Symbol | Value | Unit |
|---|-----------|-------|------|
| Reverse Voltage | V_R | 30 | V |
| Forward Current (DC) | I_F | 500 | mA |
| Forward Surge Current (60 Hz @ 1 cycle) | I_{FSM} | 3.0 | A |
| Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%) | I_{FRM} | 1.5 | A |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

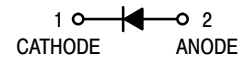


ON Semiconductor®

www.onsemi.com



YL = Specific Device Code
M = Date Code



ORDERING INFORMATION

| Device | Package | Shipping† |
|----------------|----------------------|-----------------------|
| NSR05T30XV2T5G | SOD-523 (Pb-Free) | 8000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NSR05T30XV2

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Min | Typ | Max | Unit |
|--|--------------------------|-------------|-----|------------|--------------------------|
| Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ $T_A = 25^\circ\text{C}$ | $R_{\theta JA}$ P_D | | | 489 250 | $^\circ\text{C/W}$ mW |
| Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ $T_A = 25^\circ\text{C}$ | $R_{\theta JA}$ P_D | | | 358 350 | $^\circ\text{C/W}$ mW |
| Junction and Storage Temperature Range | T_J, T_{stg} | -55 to +150 | | | $^\circ\text{C}$ |

1. Mounted onto a 4 in square FR-4 board 50 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
2. Mounted onto a 4 in square FR-4 board 650 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.

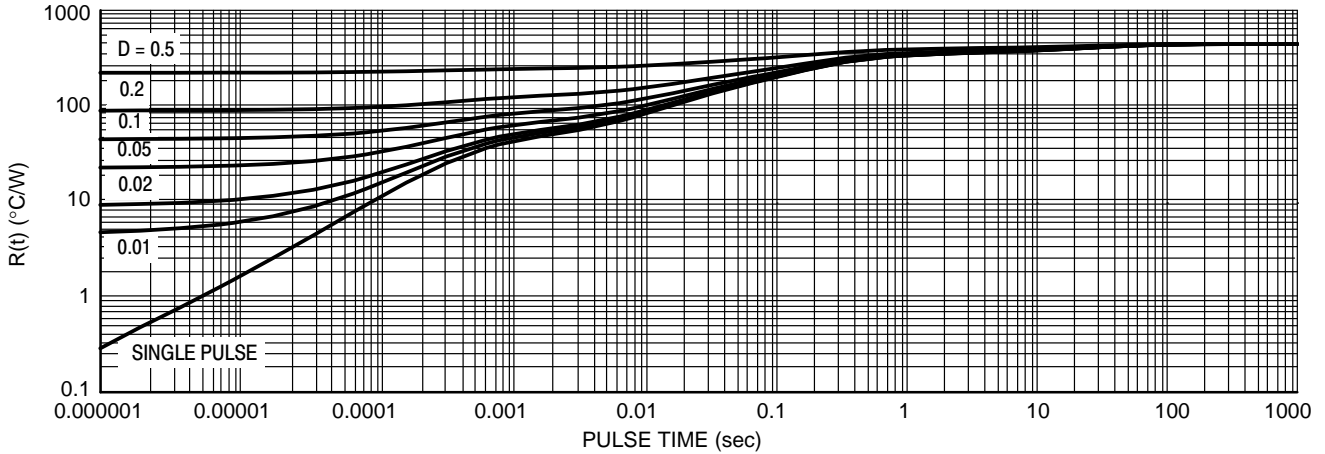


Figure 1. Thermal Response (Note 1)

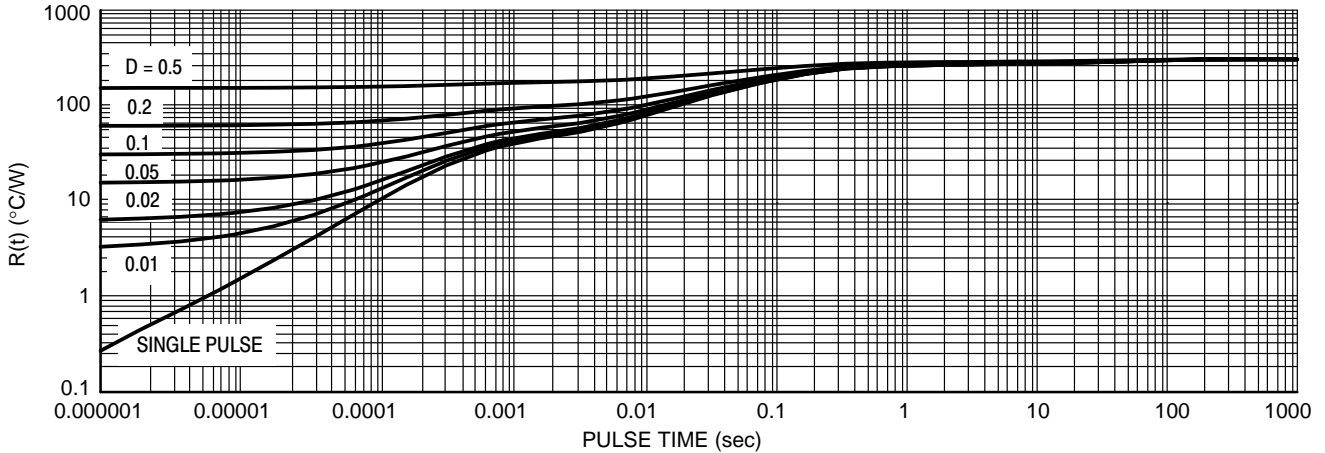
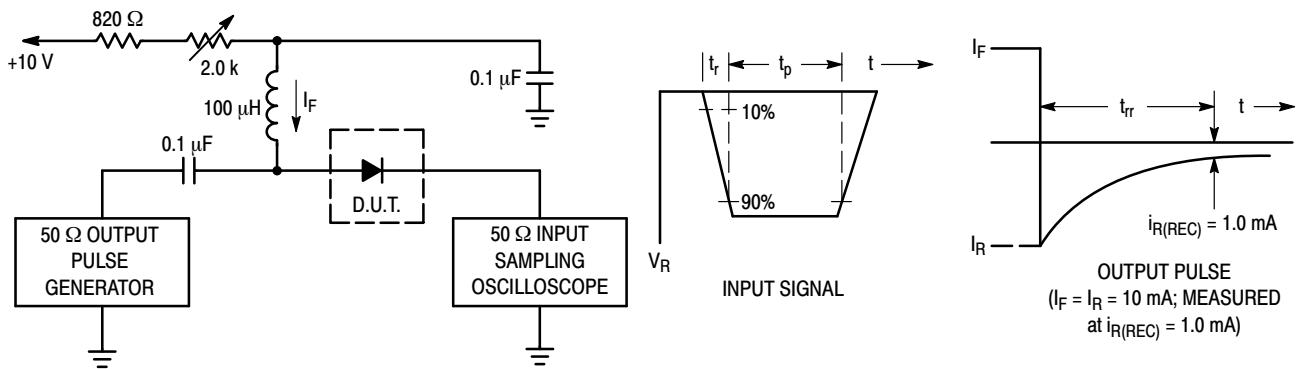


Figure 2. Thermal Response (Note 2)

NSR05T30XV2

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|--|------------------|-----|--------------------------|--------------------------|------|
| Reverse Leakage (V _R = 10 V) (V _R = 30 V) | I _R | | 30 52 | 110 170 | μA |
| Forward Voltage (I _F = 10 mA) (I _F = 100 mA) (I _F = 200 mA) (I _F = 500 mA) | V _F | | 200 275 205 370 | 340 380 420 450 | mV |
| Total Capacitance (V _R = 1.0 V, f = 1.0 MHz) | C _T | | 85 | | pF |
| Reverse Recovery Time (I _F = I _R = 10 mA, I _{R(REC)} = 1.0 mA, Figure 3) | t _{rr} | | 23 | | ns |
| Peak Forward Recovery Voltage (I _F = 100 mA, t _r = 20 ns, Figure 4) | V _{FRM} | | 395 | | mV |



- Notes: 1. A 2.0 kΩ variable resistor adjusted for a Forward Current (I_F) of 10 mA.
 2. Input pulse is adjusted so I_{R(peak)} is equal to 10 mA.
 3. t_p » t_{rr}

Figure 3. Recovery Time Equivalent Test Circuit

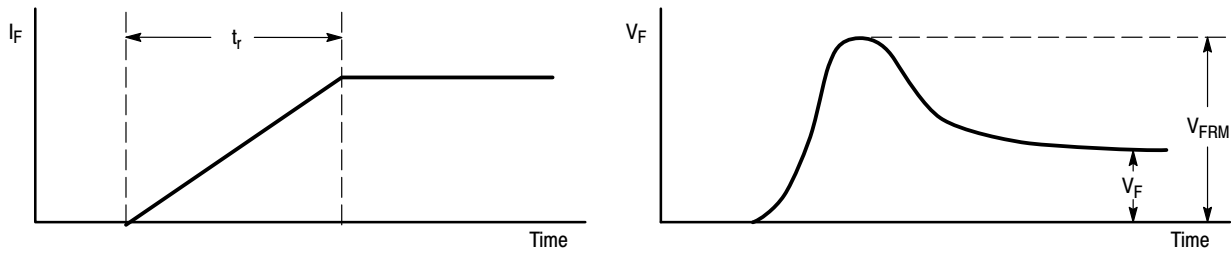


Figure 4. Peak Forward Recovery Voltage Definition

NSR05T30XV2

TYPICAL CHARACTERISTICS

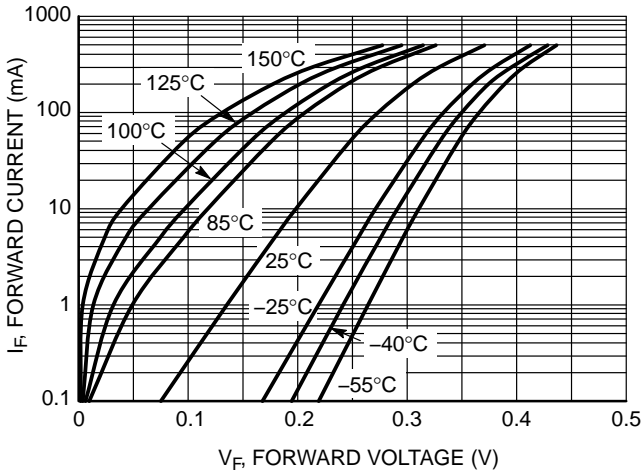


Figure 5. Forward Voltage

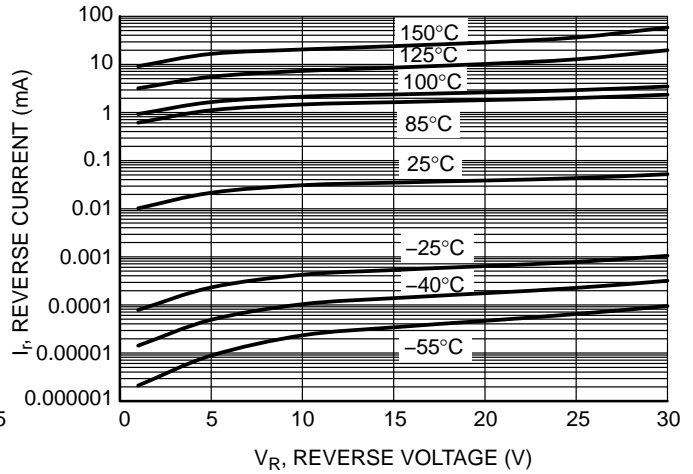


Figure 6. Leakage Current

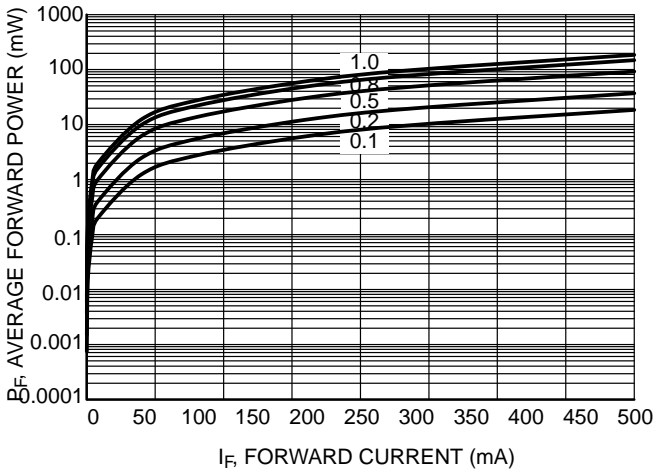


Figure 7. Average Forward Power Dissipation

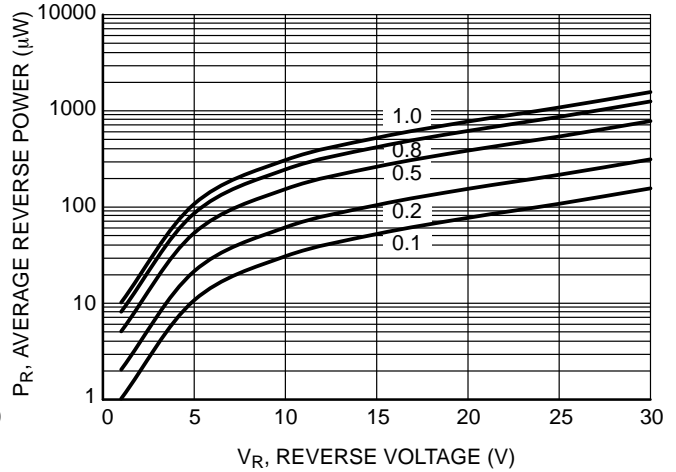


Figure 8. Average Reverse Power Dissipation

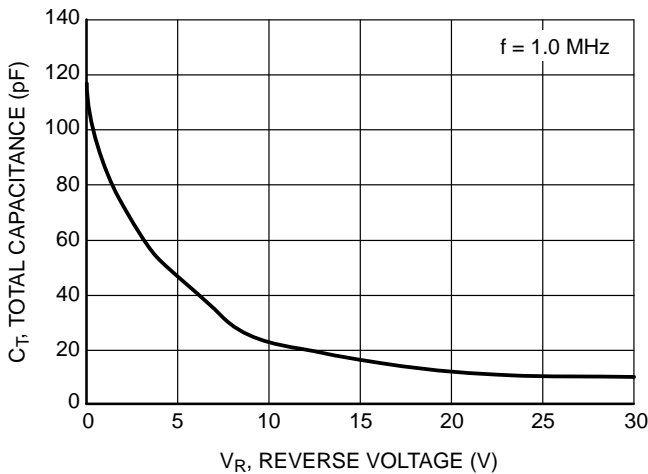


Figure 9. Total Capacitance

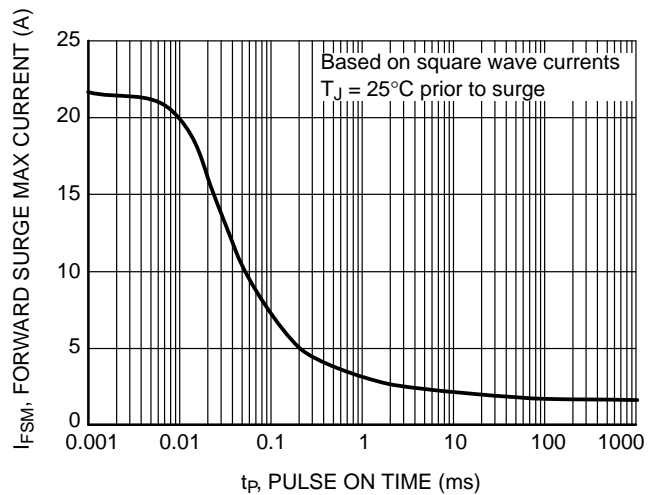
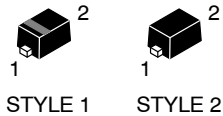


Figure 10. Forward Surge Current

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

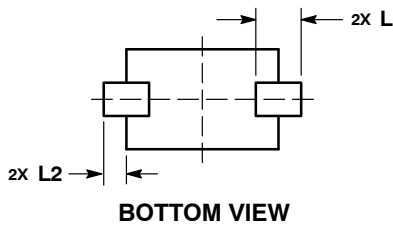
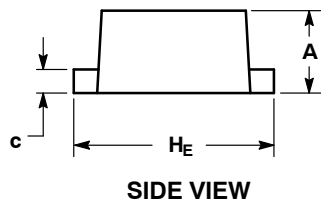
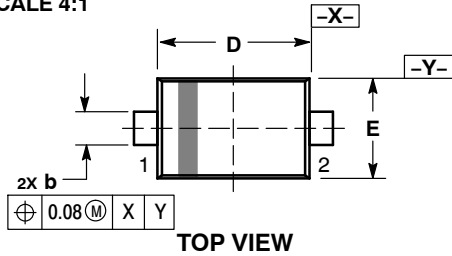
ON Semiconductor®



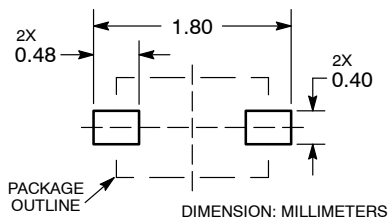
SOD-523
CASE 502-01
ISSUE E

DATE 28 SEP 2010

SCALE 4:1



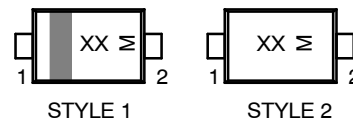
RECOMMENDED SOLDERING FOOTPRINT*



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS | | |
|----------------|-------------|------|------|
| | MIN | NOM | MAX |
| A | 0.50 | 0.60 | 0.70 |
| b | 0.25 | 0.30 | 0.35 |
| c | 0.07 | 0.14 | 0.20 |
| D | 1.10 | 1.20 | 1.30 |
| E | 0.70 | 0.80 | 0.90 |
| H _E | 1.50 | 1.60 | 1.70 |
| L | 0.30 REF | | |
| L2 | 0.15 | 0.20 | 0.25 |

GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLE 1: PIN 1. CATHODE (POLARITY BAND) 2. ANODE
STYLE 2: NO POLARITY

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

| | | |
|-------------------------|--------------------|--|
| DOCUMENT NUMBER: | 98AON11524D | Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red. |
| DESCRIPTION: | SOD-523 | PAGE 1 OF 1 |

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative